L Number	Hits	Search Text	DB	Time stamp
-	4028	(qfps qfp (quad adj flat adj packs)(quad adj flat adj package))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:02
-	304	ir near1 voltage near1 drop$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:04
-	10608	(wre wiring) with parallel	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:04
-	0	(ir near1 voltage near1 drop$4) and ((wre wiring) with parallel)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:04
-	98123	voltage near1 drop$4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:05
-	600	((wre wiring) with parallel) and (voltage near1 drop$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:05
-	3	((qfps qfp (quad adj flat adj packs)(quad adj flat adj package))) and (((wre wiring) with parallel) and (voltage near1 drop$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:05
-	72	(((wre wiring) with parallel) and (voltage near1 drop$4)) and ((bonding bond) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:06
-	69	((((wre wiring) with parallel) and (voltage near1 drop$4)) and ((bonding bond) near pad)) and (die chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:10
-	31	(die chip (integrated adj circuit)) same (((two pair) near1 ((bond bonding) adj pad)) near2 (wire wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:20
-	3860	(die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:22
-	6	"6169331"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:24
-	11	"5905639"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:25
-	9	"6097098"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:25
-	11	"5838072"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:26
-	11	"6091140"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:38
-	11	"5883427"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:38

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-	9	"6144102"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:38
-	8	"6291884"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	4	"6211461"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	8	"5793104"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	10	"5864174"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	14	"5412247"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	12	"6300685"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:39
-	2	"6218728"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:40
-	114	("6169331" "5905639" "6097098" "5838072" "6091140" "5883427" "6144102" "6291884" "6211461" "5793104" "5864174" "5412247" "6300685" "6218728") not ((((wre wiring) with parallel) and (voltage near1 drop$4)) and ((bonding bond) near pad)) not ((die chip (integrated adj circuit)) same (((two pair) near1 ((bond bonding) adj pad)) near2 (wire wiring)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:40
-	114	"6169331" "5905639" "6097098" "5838072" "6091140" "5883427" "6144102" "6291884" "6211461" "5793104" "5864174" "5412247" "6300685" "6218728"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 10:41
-	0	6472764.URPN.	USPAT	2002/12/10 10:46
-	17	("4213141" | "4403240" | "5043943" | "5303180" | "5353250" | "5354955" | "5399904" | "5455460" | "5598967" | "5612575" | "5682105" | "5763298" | "5838072" | "5880596" | "5989939" | "6097098" | "6194774").PN.	USPAT	2002/12/10 10:46
-	4	6194774.URPN.	USPAT	2002/12/10 10:53
-	27	("3614554" | "4446445" | "5024966" | "5173672" | "5221984" | "5321299" | "5376902" | "5378869" | "5394008" | "5519233" | "5572180" | "5576680" | "5639989" | "5710068" | "5736749" | "5744869" | "5767563" | "5793096" | "5849355" | "5877667" | "5880517" | "5886393" | "5912997" | "5920067" | "5929636" | "5966063" | "5973567").PN.	USPAT	2002/12/10 10:54
-	6	5989939.URPN.	USPAT	2002/12/10 11:46
-	8	("4764848" | "5148265" | "5148266" | "5455390" | "5476211" | "5801446" | "5806181" | "5829128").PN.	USPAT	2002/12/10 11:46

-	8	("5170312" | "5172471" | "5276352" | "5304737" | "5473196" | "5587607" | "5686764" | "5723906").PN.	USPAT	2002/12/10 11:49
-	17	5473196.URPN.	USPAT	2002/12/10 11:53
-	103	("3851221" | "4567643" | "4730232" | "4763188" | "4883773" | "4982265" | "4996587" | "5012323" | "5025306" | "5040052" | "5104820" | "5117282" | "5138438" | "5140404" | "5148265" | "5162260" | "5165067" | "5198888" | "5229647" | "5258330" | "5291061" | "5323060" | "5334875" | "5343366" | "5347429" | "5384689" | "5422435" | "5426072" | "5426563" | "5432318" | "5432729" | "5455740" | "5463253" | "5473196" | "5477611" | "5479318" | "5481134" | "5493476" | "5495394" | "5495398" | "5502289" | "5514907" | "5519936" | "5533256" | "5536909" | "5541812" | "5552963" | "5569625" | "5581498" | "5586009" | "5587341" | "5605592" | "5608262" | "5614766" | "5633785" | "5637536" | "5637912" | "5650593" | "5654220" | "5682062" | "5684330" | "5689135" | "5696031" | "5715147" | "5716221" | "5721452" | "5739581" | "5744284" | "5753974" | "5766987" | "5777391" | "5783870" | "5793108" | "5798014" | "5815372" | "5824177" | "5847932" | "5858815" | "5861666" | "5863813" | "5866949" | "5872025" | "5885849" | "5886412" | "5917242" | "5950070" | "5952611" | "5973403" | "5989982" | "6005778" | "6025251" | "6028354" | "RE36613" | "6043109" | "6051886" | "6057598" | "6072154" | "6072243" | "6080264" | "6184463" | "6204091" | "6214641" | "6235554").PN.	USPAT	2002/12/10 11:55
-	1	"5239447".PN.	USPAT	2002/12/10 12:05
-	17	5473196.URPN.	USPAT	2002/12/10 12:05
-	8	("5170312" | "5172471" | "5276352" | "5304737" | "5473196" | "5587607" | "5686764" | "5723906").PN.	USPAT	2002/12/10 12:08
-	1	"3688132".PN.	USPAT	2002/12/10 12:14
-	8	("5394009" | "5627408" | "5777391" | "5793104" | "5864174" | "5956233" | "5976916" | "6013948").PN.	USPAT	2002/12/10 12:19
-	5	("4897918" | "5388327" | "5490324" | "5594275" | "5990565").PN.	USPAT	2002/12/10 12:21
-	1	6211461.URPN.	USPAT	2002/12/10 12:21
-	2	6169331.URPN.	USPAT	2002/12/10 12:23

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-	43	("4080485" | "4241360" | "4359754" | "4403240" | "4750666" | "4984065" | "5036015" | "5058798" | "5081520" | "5235212" | "5298793" | "5343064" | "5355004" | "5359227" | "5367195" | "5371654" | "5384487" | "5492863" | "5539251" | "5550083" | "5559428" | "5587607" | "5650914" | "5677574" | "5681647" | "5712695" | "5723906" | "5804876" | "5808354" | "5817030" | "5818564" | "5821624" | "5828116" | "5838072" | "5854513" | "5879530" | "5909055" | "5923091" | "6008533" | "6008542" | "6013944" | "6025651" | "6028354").PN.	USPAT	2002/12/10 12:23
-	7	5714800.URPN.	USPAT	2002/12/10 12:34
-	15	("5081563" | "5126813" | "5148265" | "5148266" | "5227232" | "5258330" | "5315486" | "5319241" | "5381047" | "5402318" | "5412247" | "5414298" | "5463246" | "5491362" | "5528075").PN.	USPAT	2002/12/10 12:35
-	34	(US-6489667-$ or US-6479887-$ or US-6472764-$ or US-6194774-$ or US-6424223-$ or US-5767563-$ or US-5519233-$ or US-5376902-$ or US-6097098-$ or US-5989939-$ or US-5148265-$ or US-5473196-$ or US-5973403-$ or US-5950070-$ or US-5696031-$ or US-5495398-$ or US-5258330-$ or US-5838072-$ or US-6462407-$ or US-6445077-$ or US-6300685-$ or US-6291884-$ or US-6211461-$ or US-6169331-$ or US-6476506-$ or US-6008533-$).did. or (US-5828116-$ or US-4403240-$ or US-4359754-$ or US-6091140-$ or US-5905639-$ or US-5883427-$ or US-5714800-$).did. or (JP-2000151223-$).did.	USPAT; DERWENT	2002/12/10 12:40
-	4	("6169331" "5905639" "6097098" "5838072" "6091140" "5883427" "6144102" "6291884" "6211461" "5793104" "5864174" "5412247" "6300685" "6218728") and (stitch adj bond)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 13:08
-	10	("6169331" "5905639" "6097098" "5838072" "6091140" "5883427" "6144102" "6291884" "6211461" "5793104" "5864174" "5412247" "6300685" "6218728") and ((ball adj bond)(stitch adj bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 13:18
-	14	("5359227" | "5468999" | "5691568" | "5796171" | "5801450" | "5962926" | "6121690" | "6148505" | "6160313" | "6169331" | "6215182" | "6291898" | "6297078" | "6307271" | "2001/0017411" | "2002/0011654" | "2002/0024146").PN.	USPAT	2002/12/10 13:14
-	238	((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond)(stitch adj bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:38
-	104	((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and (((ball adj bond)(stitch adj bond)) near3 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:39
-	22	((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond) near3 (ball pad)) and ((stitch adj bond) near3 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:40

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-	15	((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond) near2 (ball pad)) and ((stitch adj bond) near2 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/10 13:30
-	2	5989939.pn. and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 09:59
-	0	5989939.pn. and (gold copper aluminum)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 10:02
-	1	5989939.pn. and trace	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 10:23
-	6	"6169331"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 10:28
-	3	"6169331" and ((stitch adj bond) (ball adj bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/12/11 10:29
-	8	("4393392" | "4720915" | "4751482" | "5006673" | "5371405" | "5616952" | "5677570" | "5789816").PN.	USPAT	2003/06/15 12:05
-	10	5838072.URPN.	USPAT	2003/06/15 12:06
-	0	6351040.URPN.	USPAT	2003/06/15 12:14
-	17	("4213141" | "4403240" | "5043943" | "5303180" | "5353250" | "5354955" | "5399904" | "5455460" | "5598967" | "5612575" | "5682105" | "5763298" | "5838072" | "5880596" | "5989939" | "6097098" | "6194774").PN.	USPAT	2003/06/15 12:14
-	0	6348400.URPN.	USPAT	2003/06/15 12:19
-	17	("4213141" | "4403240" | "5043943" | "5303180" | "5353250" | "5354955" | "5399904" | "5455460" | "5598967" | "5612575" | "5682105" | "5763298" | "5838072" | "5880596" | "5989939" | "6097098" | "6194774").PN.	USPAT	2003/06/15 12:19
-	288	((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond)(stitch adj bond))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:38
-	132	((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and (((ball adj bond)(stitch adj bond)) near3 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:39
-	38	(((die chip (integrated adj circuit)) same (((bond bonding) adj pad) near2 (wire wiring))) and ((ball adj bond)(stitch adj bond))) and ((stitch adj bond) near3 (ball pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 08:40

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